



Material Content Data Sheet



Sales Product Name				BGM 13HBA12 E6327		Issued		3. July 2019	
MA#				MA005343352					
Package				PG-ATSLP-12-13		Weight*		2.29 mg	
Construction Element	Material Group	Substances	CAS# if applicable	Weight [mg]	Average Mass [%]	Sum [%]	Average Mass [ppm]	Sum [ppm]	
chip	inorganic material	silicon	7440-21-3	0.452	19.76	19.76	197571	197571	
bumps	non noble metal	copper	7440-50-8	0.022	0.94	0.94	9427	9427	
encapsulation	organic material	carbon black	1333-86-4	0.006	0.26		2599		
	plastics	epoxy resin	-	0.172	7.54		75375		
	inorganic material	silicondioxide	60676-86-0	1.011	44.17	51.97	441855	519829	
leadfinish	noble metal	gold	7440-57-5	0.034	1.47		14745		
	non noble metal	nickel	7440-02-0	0.038	1.68	3.15	16817	31562	
substrate	organic material	carbon black	1333-86-4	0.001	0.03		271		
	plastics	epoxy resin	-	0.024	1.06		10568		
	inorganic material	silicondioxide	60676-86-0	0.182	7.95		79482		
	non noble metal	copper	7440-50-8	0.315	13.76	22.80	137605	227926	
solder	noble metal	silver	7440-22-4	0.000	0.01		62		
	non noble metal	tin	7440-31-5	0.008	0.34	0.35	3358	3420	
ubm	non noble metal	titanium	7440-32-6	0.000	0.00		11		
	non noble metal	copper	7440-50-8	0.000	0.01	0.01	91	102	
solder resists	inorganic material	silicondioxide	60676-86-0	0.005	0.22		2160		
	inorganic material	bariumsulfate	7727-43-7	0.005	0.22		2185		
	plastics	acrylic resin	-	0.013	0.58	1.02	5818	10163	
*deviation	< 10%			Sum in total:		100.00		1000000	

Important Remarks:

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This product is in compliance with EU Directive 2015/863/EU amending Annex II to EU Directive 2011/65/EU (RoHS) and does not use any exemption

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